

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Original) A photosensitive resin composition comprising:
 - (A) a polymer having an acid functional group and/or a substituent derived therefrom;
 - (B) a compound having at least one substituent derived from an amine functional group;
 - (C) a photoreactive compound; and
 - (D) a solvent.
2. (Original) The photosensitive resin composition according to claim 1, wherein the compound of the component (B) further has at least one acid functional group and/or substituent derived therefrom.
3. (Original) The photosensitive resin composition according to claim 1, wherein the compound of the component (B) has one substituent or two substituents derived from an amine functional group.
4. (Original) The photosensitive resin composition according to claim 3, wherein the component (B) has one or two acid functional group and/or substituent derived therefrom.

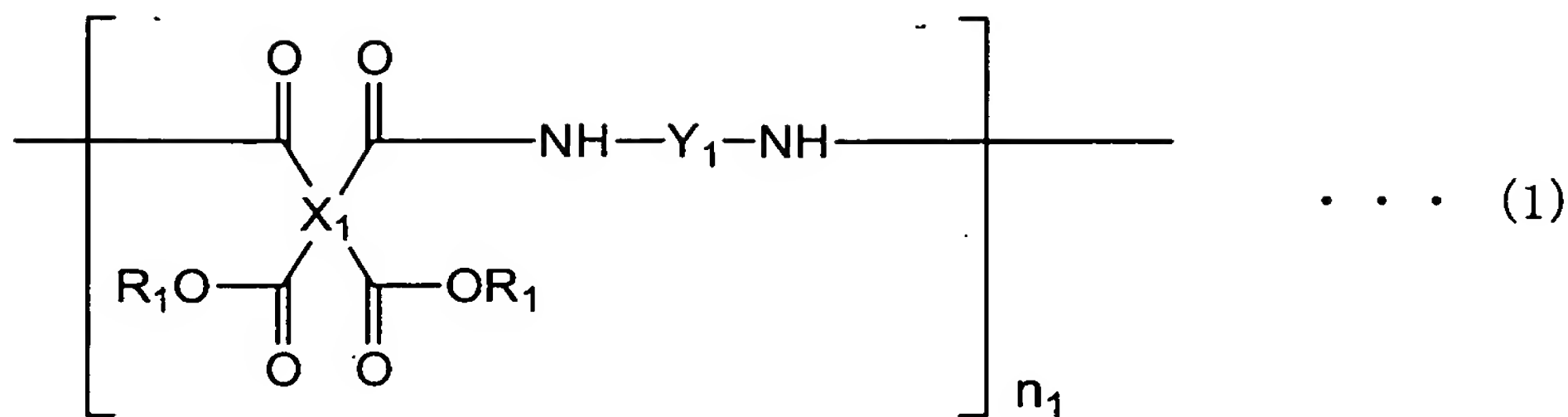
5. (Original) The photosensitive resin composition according to claim 1, wherein the component (A) further has at least one substituent derived from an amine functional group in itself or in another component (A), and wherein the component (B) further has at least one acid functional group and/or substituent derived therefrom.

6. (Original) The photosensitive resin composition according to claim 5, wherein the component (A) has one substituent derived from an amine functional group, and wherein the component (B) has one substituent or two substituents derived from an amine functional group and has one acid functional group and/or substituent derived therefrom.

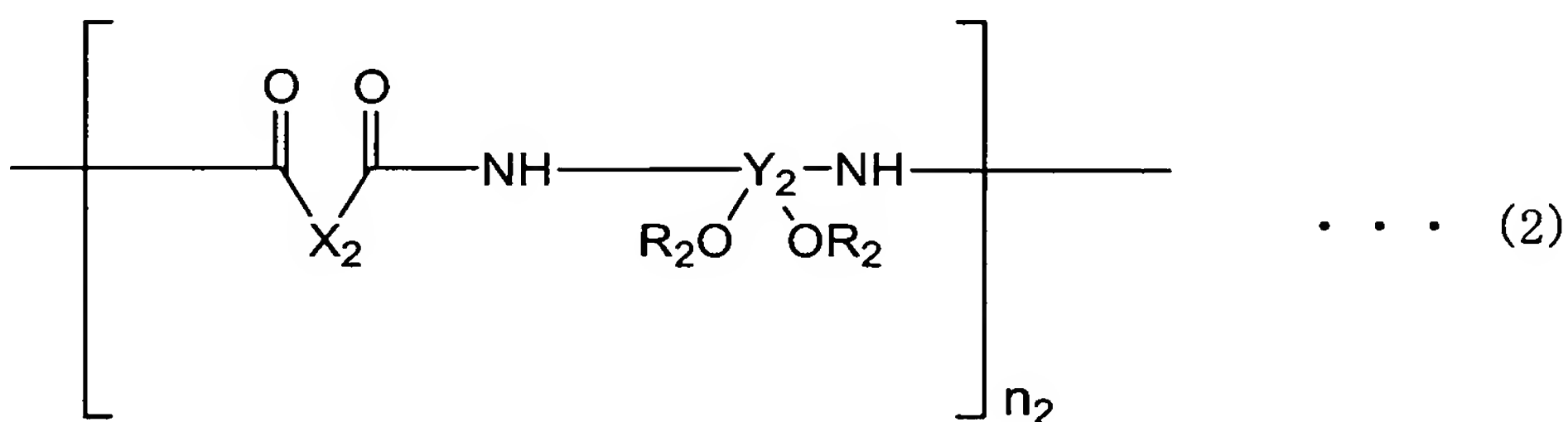
7. (Original) The photosensitive resin composition according to claim 1, wherein the polymer (A) is a heat-resistant polymer.

8. (Original) The photosensitive resin composition according to claim 1, wherein the acid functional group in the polymer (A) is a carboxyl group and/or a phenolic hydroxyl group.

9. (Currently amended) The photosensitive resin composition according to claim 7 ~~or 8~~, wherein the heat-resistant polymer is a polyimide precursor represented by the general formula (1) below or polyimide derived from the precursor, a polybenzoxazole precursor represented by the general formula (2) below or polybenzoxazole derived from the precursor, a copolymer thereof, or a mixture thereof:



wherein X_1 represents a tetravalent organic group, Y_1 represents a divalent organic group, R_1 represents hydrogen or a monovalent organic group, and n_1 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer,



wherein X_2 represents a divalent organic group, Y_2 represents a tetravalent organic group, of which two valences are used in bonding to hydroxyl groups, R_2 represents hydrogen or a monovalent organic group, and n_2 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer.

10. (Original) A method for forming a pattern, comprising:
 a step of applying the photosensitive resin composition according to claim 1
 onto a substrate and drying it;

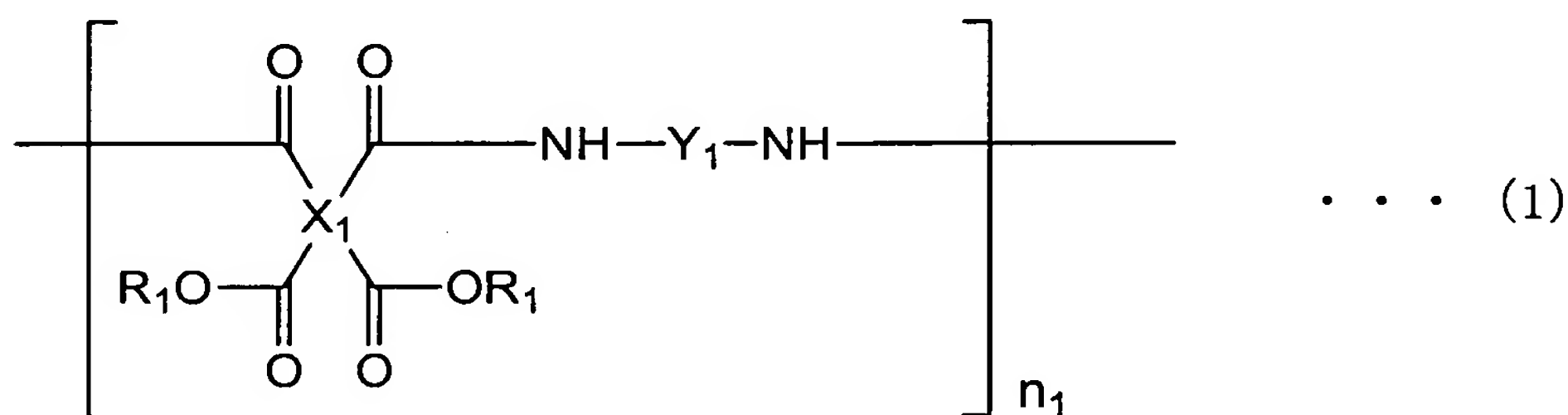
a step of subjecting the applied and dried photosensitive resin film to light exposure;

a step of subjecting the exposed photosensitive resin film to development using an alkaline aqueous solution; and

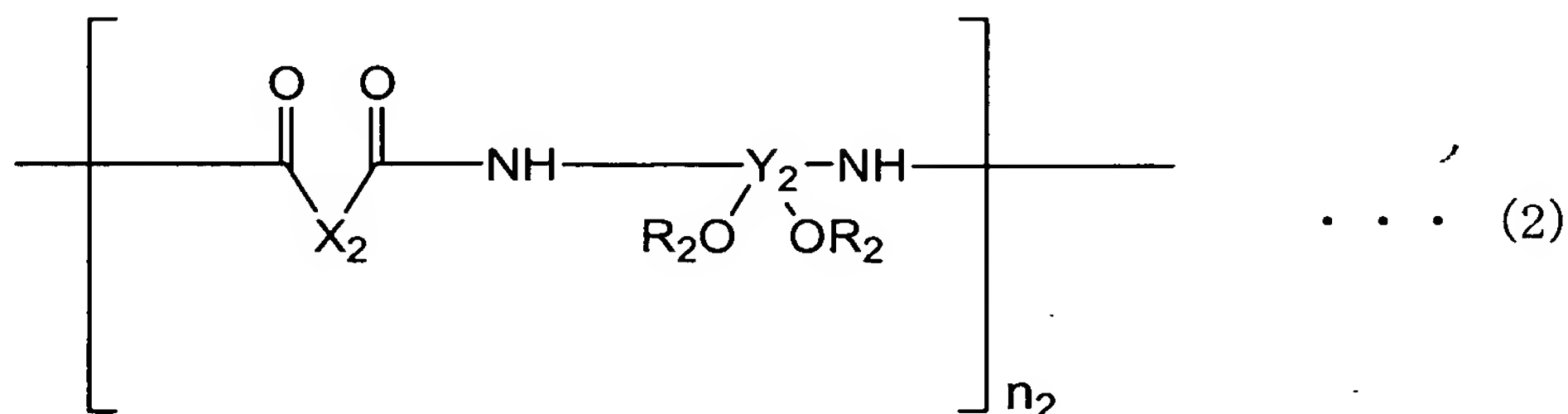
a step of subjecting the pattern obtained in the development to heat treatment.

11. (Original) An electronic part having an electronic device having the pattern obtained by the method according to claim 10, wherein the pattern is an interlayer dielectric layer and/or a surface protecting film layer.

12. (New) The photosensitive resin composition according to claim 8, wherein the heat-resistant polymer is a polyimide precursor represented by the general formula (1) below or polyimide derived from the precursor, a polybenzoxazole precursor represented by the general formula (2) below or polybenzoxazole derived from the precursor, a copolymer thereof, or a mixture thereof:



wherein X_1 represents a tetravalent organic group, Y_1 represents a divalent organic group, R_1 represents hydrogen or a monovalent organic group, and n_1 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer,



wherein X_2 represents a divalent organic group, Y_2 represents a tetravalent organic group, of which two valences are used in bonding to hydroxyl groups, R_2 represents hydrogen or a monovalent organic group, and n_2 represents an integer of 2 to 500 corresponding to the number of the repeating units of the polymer.